

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT4275366

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MEILIANG WANG	01/26/2017
XINJIAN LEI	01/25/2017
ANUPAMA MALLIKARJUNAN	01/26/2017
HARIPIN CHANDRA	01/25/2017
BING HAN	01/26/2017
RECEIVING PARTY DATA	
Name:	VERSUM MATERIALS US, LLC
Street Address:	7201 HAMILTON BLVD.
Internal Address:	PATENT DEPT.
City:	ALLENTOWN
State/Country:	PENNSYLVANIA
Postal Code:	18195-1501
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15404376
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	07945ZP USA
NAME OF SUBMITTER:	MICHAEL K. BOYER
SIGNATURE:	/Michael K. Boyer/
DATE SIGNED:	02/15/2017
This document serves as an Oath/Declaration (37 CFR 1.63).	

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Total Attachments: 2

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ASSIGNMENT & DECLARATION

For value received, we, Meiliang Wang, Xinjian Lei, Anupama Mallikarjunan, Haripin Chandra and Bing Han, hereby sell, assign, and transfer to **VERSUM MATERIALS US, LLC**, a corporation of the State of Delaware, having an office at 7201 Hamilton Boulevard, Allentown, PA 18195-1501, the entire right, title, and interest in and to the invention relating to

**HIGH TEMPERATURE ATOMIC LAYER DEPOSITION OF
SILICON-CONTAINING FILMS**

described in our application for Letters Patent of the United States (identified by Docket No. 07945ZP USA; and/or Appl. No. 15/404,376; filed on 12 January 2017), in and to all Letters Patent which may be issued upon said application, in and to any divisional or reissue applications based thereon, and in and to all Letters Patent upon said invention or improvements which may be granted in foreign countries. We hereby also assign and convey to said **VERSUM MATERIALS US, LLC**, all the rights accruing to us by virtue of the International Convention for the Protection of Industrial Property (Art. 4), including the right to apply for and to have patents issued in its own name.

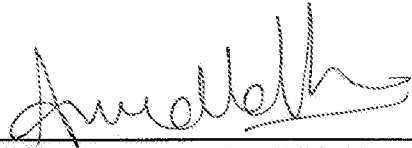
And we hereby authorize and request the Commissioner of Patents and Trademarks of the United States and the Officials of the Patent Offices of all other countries to issue the Letters Patent of their respective countries to said **VERSUM MATERIALS US, LLC**, as assignee of the entire right, title, and interest in and to the same.

And we hereby promise and agree to execute all papers and perform all acts necessary to secure to and vest in said **VERSUM MATERIALS US, LLC**, its successors and assigns, the rights conveyed as herein set forth.

And I hereby authorize the above-mentioned Assignee or its legal representative to insert in the instrument the application serial number of aforesaid application or any other information that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office.

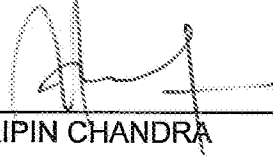
And we hereby declare that the above-identified application was made or authorized to be made by me. I believe I am the original inventor or an original joint inventor of a claimed invention in the application. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

<p><i>Meiliang Wang</i> (L.S.) <hr style="border: 0; border-top: 1px solid black; margin: 0;"/> MEILIANG WANG <i>January 26, 2017</i> <hr style="border: 0; border-top: 1px solid black; margin: 0;"/> Date</p>	<p><i>Xinjian Lei</i> (L.S.) <hr style="border: 0; border-top: 1px solid black; margin: 0;"/> XINJIAN LEI <i>January 25, 2017</i> <hr style="border: 0; border-top: 1px solid black; margin: 0;"/> Date</p>
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ANUPAMA MALLIKARJUNAN (L.S.)

January 26, 2017
Date



HARIPIN CHANDRA (L.S.)

January 25, 2017
Date



BING HAN (L.S.)

January 26, 2017
Date